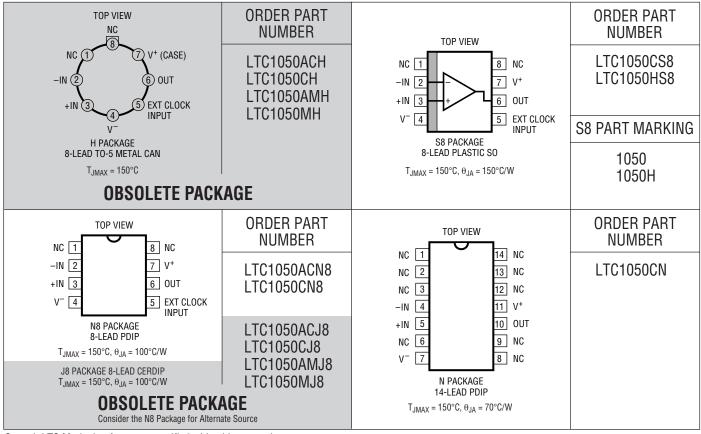
## **ABSOLUTE MAXIMUM RATINGS (Note 1)**

Total Supply Voltage (V <sup>+</sup> to V <sup>-</sup> )	18V
Input Voltage (V+ + 0.3V)	to $(V^ 0.3V)$
Output Short-Circuit Duration	Indefinite
Storage Temperature Range6	65°C to 150°C
Lead Temperature (Soldering, 10 sec)	300°C

Operating Temperature Range	
LTC1050AC/C	40°C to 85°C
LTC1050H	-40°C to 125°C
LTC1050AM/M (OBSOLETE)	. −55°C to 125°C

## PACKAGE/ORDER INFORMATION



Consult LTC Marketing for parts specified with wider operating temperature ranges.

# **ELECTRICAL CHARACTERISTICS** The $\bullet$ denotes specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^{\circ}C$ . $V_S = \pm 5V$

		LTC1050AM			LTC1050AC				
PARAMETER	CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Input Offset Voltage	(Note 3)			±0.5	±5		±0.5	±5	μV
Average Input Offset Drift	(Note 3)	•		±0.01	±0.05		±0.01	±0.05	μV/°C
Long Term Offset Voltage Drift				50			50		nV/√Mo
Input Offset Current	(Note 5)	•		±20	±60 ±300		±20	±60 ±150	pA pA
Input Bias Current	(Note 5)	•		±10	±30 ±2000		±10	±30 ±100	pA pA
Input Noise Voltage	0.1Hz to 10Hz (Note 6) DC to 1Hz			1.6 0.6	2.1		1.6 0.6	2.1	μV <sub>P-P</sub> μV <sub>P-P</sub>
		•							1050fb



# **ELECTRICAL CHARACTERISTICS** The $\bullet$ denotes specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^{\circ}\text{C}$ . $V_S = \pm 5\text{V}$

			_	TC1050A			.TC1050A	_	
PARAMETER	CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Input Noise Current	f = 10Hz (Note 4)			1.8			1.8		fA/√Hz
Common Mode Rejection Ratio	$V_{CM} = V^- \text{ to } 2.7V$	•	114 110	140		114 110	140		dB dB
Power Supply Rejection Ratio	$V_S = \pm 2.375 \text{V to } \pm 8 \text{V}$	•	125	140		125	140		dB
Large-Signal Voltage Gain	$R_L = 10k, V_{OUT} = \pm 4V$	•	130	160		130	160		dB
Maximum Output Voltage Swing	R <sub>L</sub> = 10k R <sub>L</sub> = 100k	•	±4.7	±4.85 ±4.95		±4.7	±4.85 ±4.95		V
Slew Rate	R <sub>L</sub> = 10k, C <sub>L</sub> = 50pF			4			4		V/µs
Gain Bandwidth Product				2.5			2.5		MHz
Supply Current	No Load	•		1	1.5 2.3		1	1.5 2.3	mA mA
Internal Sampling Frequency				2.5			2.5		kHz

# The ullet denotes specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^{\circ}C$ . $V_S = \pm 5V$

		LTC1050M/H			LTC1050C				
PARAMETER	CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Input Offset Voltage	(Note 3)			±0.5	±5		±0.5	±5	μV
Average Input Offset Drift	(Note 3)	•		±0.01	±0.05		±0.01	±0.05	μV/°C
Long Term Offset Voltage Drift				50			50		nV/√Mo
Input Offset Current	(Note 5)	•		±20	±100 ±300		±20	±125 ±200	pA pA
Input Bias Current	(Note 5)	•		±10	±50 ±2000		±10	±75 ±150	pA pA
Input Noise Voltage	$R_S$ = 100 $\Omega$ , 0.1Hz to 10Hz (Note 6) $R_S$ = 100 $\Omega$ , DC to 1Hz			1.6 0.6			1.6 0.6		μV <sub>P-P</sub> μV <sub>P-P</sub>
Input Noise Current	f = 10Hz (Note 4)			1.8			1.8		fA/√Hz
Common Mode Rejection Ratio	V <sub>CM</sub> = V <sup>-</sup> to 2.7V LTC1050M/C LTC1050H	•	114 110 100	130		114 110	130		dB dB dB
Power Supply Rejection Ratio	$V_S = \pm 2.375 V$ to $\pm 8 V$ , LTC1050M/C LTC1050H	•	120 110	140		120	140		dB dB
Large-Signal Voltage Gain	$R_L = 10k, V_{OUT} = \pm 4V$	•	120	160		120	160		dB
Maximum Output Voltage Swing	R <sub>L</sub> = 10k R <sub>L</sub> = 100k	•	±4.7	±4.85 ±4.95		±4.7	±4.85 ±4.95		V
Slew Rate	$R_L = 10k, C_L = 50pF$			4			4		V/µs
Gain Bandwidth Product				2.5			2.5		MHz
Supply Current	No Load	•		1	1.5 2.3		1	1.5 2.3	mA mA
Internal Sampling Frequency				2.5			2.5		kHz

**Note 1:** Absolute Maximum Ratings are those values beyond which the life of the device may be impaired.

**Note 2:** Connecting any terminal to voltages greater than  $V^+$  or less than  $V^-$  may cause destructive latchup. It is recommended that no sources operating from external supplies be applied prior to power-up of the LTC1050.

**Note 3:** These parameters are guaranteed by design. Thermocouple effects preclude measurement of these voltage levels in high speed automatic test systems.  $V_{OS}$  is measured to a limit determined by test equipment capability.

**Note 4:** Current Noise is calculated from the formula: In =  $\sqrt{(2q \cdot lb)}$  where q = 1.6 • 10<sup>-19</sup> Coulomb.

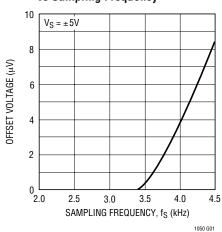
**Note 5:** At  $T_A \le 0^{\circ}C$  these parameters are guaranteed by design and not tested

**Note 6:** Every lot of LTC1050AM and LTC1050AC is 100% tested for Broadband Noise at 1kHz and sample tested for Input Noise Voltage at 0.1Hz to 10Hz.

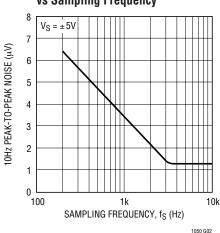


## TYPICAL PERFORMANCE CHARACTERISTICS

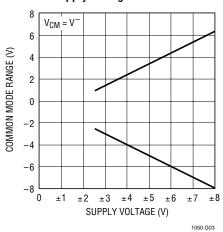




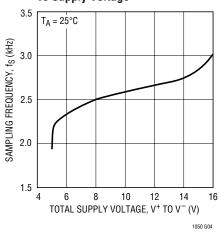
# 10Hz<sub>P-P</sub> Noise vs Sampling Frequency



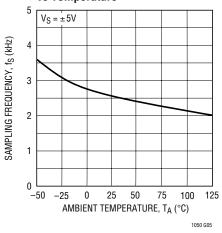
# Common Mode Input Range vs Supply Voltage



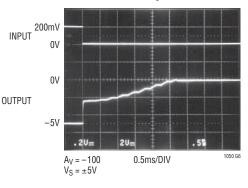
# Sampling Frequency vs Supply Voltage



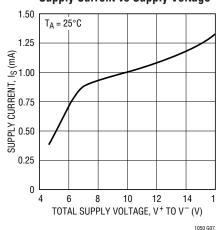
# Sampling Frequency vs Temperature



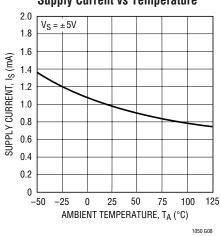
#### **Overload Recovery**



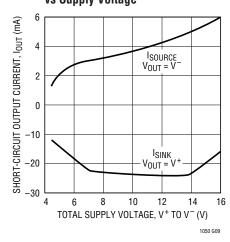
#### **Supply Current vs Supply Voltage**



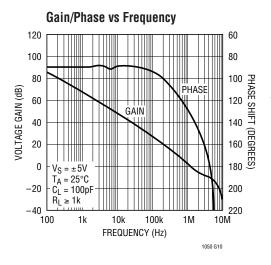
### Supply Current vs Temperature



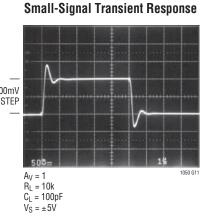
# Short-Circuit Output Current vs Supply Voltage



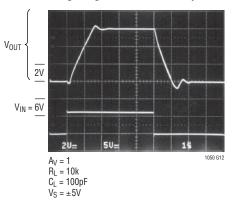
## TYPICAL PERFORMANCE CHARACTERISTICS



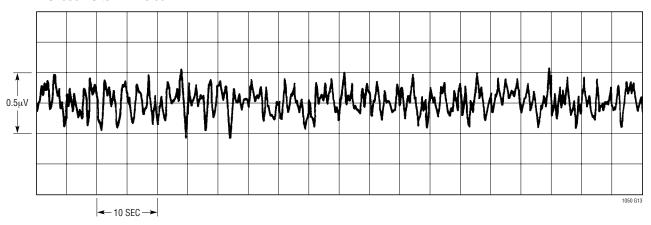




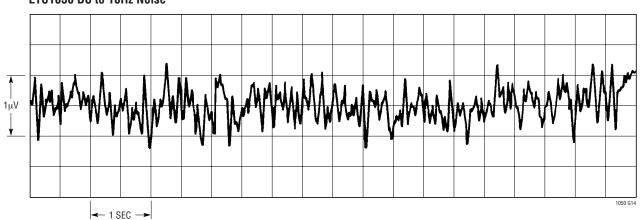
#### **Large-Signal Transient Response**



#### LTC1050 DC to 1Hz Noise

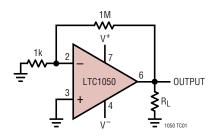


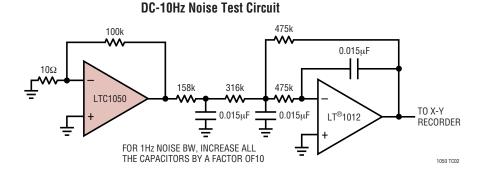
#### LTC1050 DC to 10Hz Noise



### **TEST CIRCUITS**

#### **Electrical Characteristics Test Circuit**





### APPLICATIONS INFORMATION

# ACHIEVING PICOAMPERE/MICROVOLT PERFORMANCE

#### **Picoamperes**

In order to realize the picoampere level of accuracy of the LTC1050, proper care must be exercised. Leakage currents in circuitry external to the amplifier can significantly degrade performance. High quality insulation should be used (e.g., Teflon, Kel-F); cleaning of all insulating surfaces to remove fluxes and other residues will probably be necessary—particularly for high temperature performance. Surface coating may be necessary to provide a moisture barrier in high humidity environments.

Board leakage can be minimized by encircling the input connections with a guard ring operated at a potential close to that of the inputs: in inverting configurations the guard ring should be tied to ground; in noninverting connections to the inverting input (see Figure 1). Guarding both sides of the printed circuit board is required. Bulk leakage reduction depends on the guard ring width.

#### **Microvolts**

Thermocouple effect must be considered if the LTC1050's ultralow drift is to be fully utilized. Any connection of dissimilar metals forms a thermoelectric junction producing an electric potential which varies with temperature (Seebeck effect). As temperature sensors, thermocouples exploit this phenomenon to produce useful information. In low drift amplifier circuits the effect is a primary source of error.

Connectors, switches, relay contacts, sockets, resistors, solder and even copper wire are all candidates for thermal

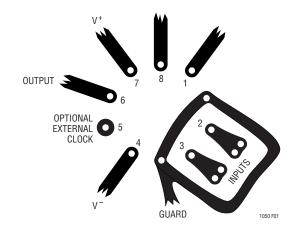


Figure 1

EMF generation. Junctions of copper wire from different manufacturers can generate thermal EMFs of  $200nV/^{\circ}C$ —4 times the maximum drift specification of the LTC1050. The copper/kovar junction, formed when wire or printed circuit traces contact a package lead, has a thermal EMF of approximately  $35\mu V/^{\circ}C$ —700 times the maximum drift specification of the LTC1050.

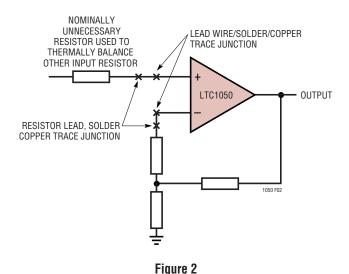
Minimizing thermal EMF-induced errors is possible if judicious attention is given to circuit board layout and component selection. It is good practice to minimize the number of junctions in the amplifier's input signal path. Avoid connectors, sockets, switches and relays where possible. In instances where this is not possible, attempt to balance the number and type of junctions so that differential cancellation occurs. Doing this may involve deliberately introducing junctions to offset unavoidable junctions.





### APPLICATIONS INFORMATION

Figure 2 is an example of the introduction of an unnecessary resistor to promote differential thermal balance. Maintaining compensating junctions in close physical proximity will keep them at the same temperature and reduce thermal EMF errors.



When connectors, switches, relays and/or sockets are necessary they should be selected for low thermal EMF activity. The same techniques of thermally balancing and coupling the matching junctions are effective in reducing the thermal EMF errors of these components.

Resistors are another source of thermal EMF errors. Table 1 shows the thermal EMF generated for different resistors. The temperature gradient across the resistor is important, not the ambient temperature. There are two junctions formed at each end of the resistor and if these junctions are at the same temperature, their thermal EMFs will cancel each other. The thermal EMF numbers are approximate and vary with resistor value. High values give higher thermal EMF.

Table 1. Resistor Thermal EMF

RESISTOR TYPE	THERMAL EMF/°C GRADIENT
Tin Oxide	~mV/°C
Carbon Composition	~450µV/°C
Metal Film	~20µV/°C
Wire Wound Evenohm	~2μV/°C
Manganin	~2μV/°C ~2μV/°C

#### PACKAGE-INDUCED OFFSET VOLTAGE

Package-induced thermal EMF effects are another important source of errors. It arises at the copper/kovar junctions formed when wire or printed circuit traces contact a package lead. Like all the previously mentioned thermal EMF effects, it is outside the LTC1050's offset nulling loop and cannot be cancelled. The input offset voltage specification of the LTC1050 is actually set by the package-induced warm-up drift rather than by the circuit itself. The thermal time constant ranges from 0.5 to 3 minutes, depending upon package type.

#### OPTIONAL EXTERNAL CLOCK

An external clock is not required for the LTC1050 to operate. The internal clock circuit of the LTC1050 sets the nominal sampling frequency at around 2.5kHz. This frequency is chosen such that it is high enough to remove the amplifier 1/f noise, yet still low enough to allow internal circuits to settle. The oscillator of the internal clock circuit has a frequency 4 times the sampling frequency and its output is brought out to Pin 5 through a 2k resistor. When the LTC1050 operates without using an external clock, Pin 5 should be left floating and capacitive loading on this pin should be avoided. If the oscillator signal on Pin 5 is used to drive other external circuits, a buffer with low input capacitance is required to minimize loading on this pin. Figure 3 illustrates the internal sampling frequency versus capacitive loading at Pin 5.

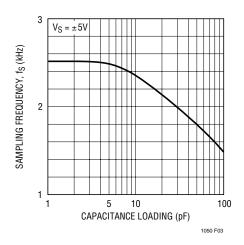


Figure 3. Sampling Frequency vs Capacitance Loading at Pin 5



### APPLICATIONS INFORMATION

When an external clock is used, it is directly applied to Pin 5. The internal oscillator signal on Pin 5 has very low drive capability and can be overdriven by any external signal. When the LTC1050 operates on  $\pm 5V$  power supplies, the external clock level is TTL compatible.

Using an external clock can affect performance of the LTC1050. Effects of external clock frequency on input offset voltage and input noise voltage are shown in the Typical Performance Characteristics section. The sampling frequency is the external clock frequency divided by 4. Input bias currents at temperatures below 100°C are dominated by the charge injection of input switches and they are basically proportional to the sampling frequency. At higher temperatures, input bias currents are mainly due to leakage currents of the input protection devices and are insensitive to the sampling frequency.

#### LOW SUPPLY OPERATION

The minimum supply for proper operation of the LTC1050 is typically below 4V ( $\pm$ 2V). In single supply applications,

PSRR is guaranteed down to 4.7V ( $\pm 2.35V$ ) to ensure proper operation down to the minimum TTL specified voltage of 4.75V.

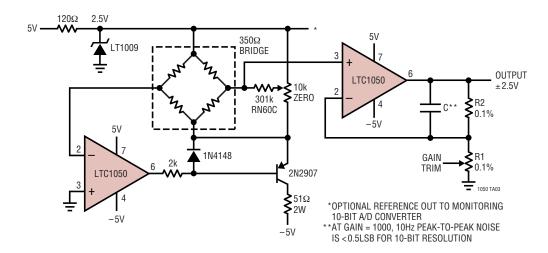
#### PIN COMPATIBILITY

The LTC1050 is pin compatible with the 8-pin versions of 7650, 7652 and other chopper-stabilized amplifiers. The 7650 and 7652 require the use of two external capacitors connected to Pin 1 and Pin 8 that are not needed for the LTC1050. Pin 1 and Pin 8 of the LTC1050 are not connected internally while Pin 5 is an optional external clock input pin. The LTC1050 can be a direct plug-in for the 7650 and 7652 even if the two capacitors are left on the circuit board.

In applications operating from below 16V total power supply, ( $\pm 8V$ ), the LTC1050 can replace many industry standard operational amplifiers such as the 741, LM101, LM108, OP07, etc. For devices like the 741 and LM101, the removal of any connection to Pin 5 is all that is needed.

### TYPICAL APPLICATIONS

#### Strain Gauge Signal Conditioner with Bridge Excitation

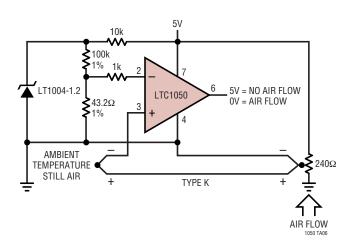


**TLINEAR** 

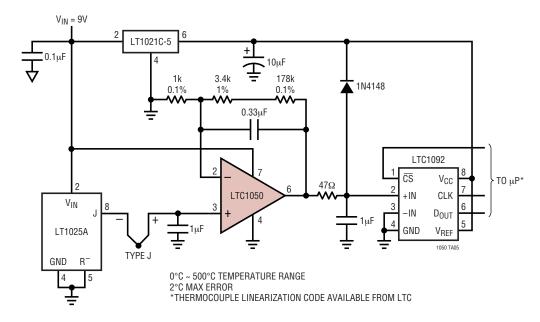
#### Single Supply Thermocouple Amplifier

## 

#### Air Flow Detector



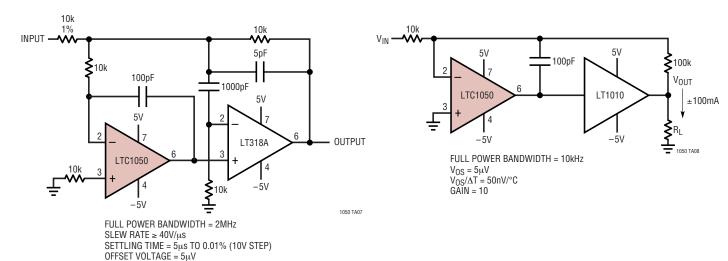
#### Battery-Operated Temperature Monitor with 10-Bit Serial Output A/D



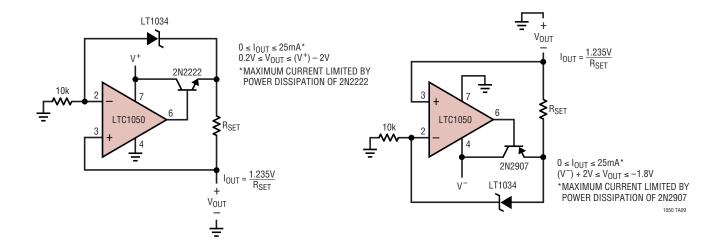
OFFSET DRIFT = 50nV/°C

#### **Fast Precision Inverter**

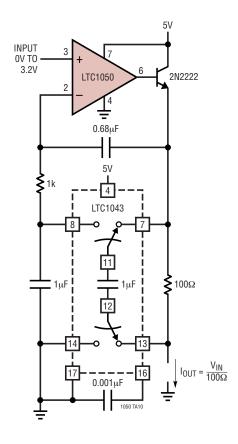
#### ±100mA Output Drive



#### **Ground Referred Precision Current Sources**

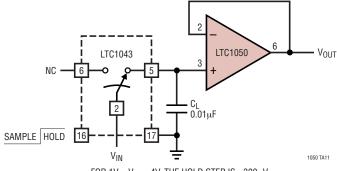


# Precision Voltage Controlled Current Source with Ground Referred Input and Output

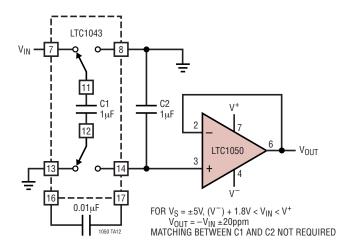


#### Sample-and-Hold Amplifier

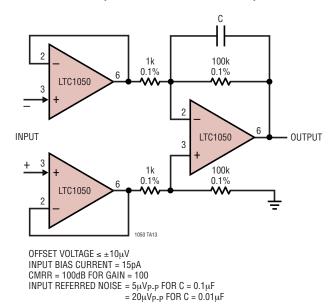
#### Ultraprecision Voltage Inverter



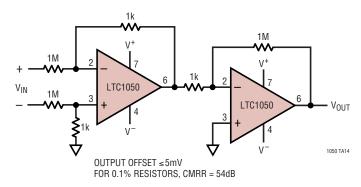
FOR 1V  $\leq$   $V_{IN}$   $\leq$  4V, THE HOLD STEP IS  ${\rm \pm}300\mu$ V. ACQUISTION TIME IS DETERMINED BY THE SWITCH  $R_{ON}$ . CL TIME CONSTANT



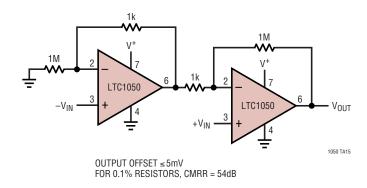
#### Instrumentation Amplifier with Low Offset and Input Bias Current



#### Instrumentation Amplifier with 100V Common Mode Input Voltage

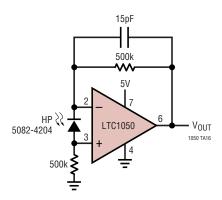


#### **Single Supply Instrumentation Amplifier**

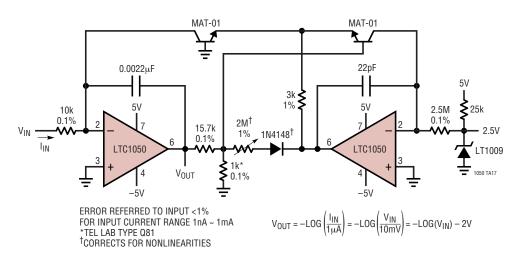




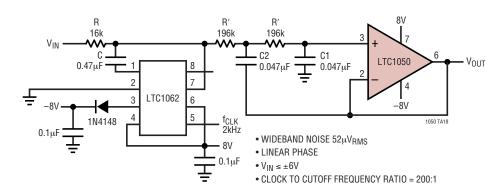
#### **Photodiode Amplifier**



#### 6 Decade Log Amplifier

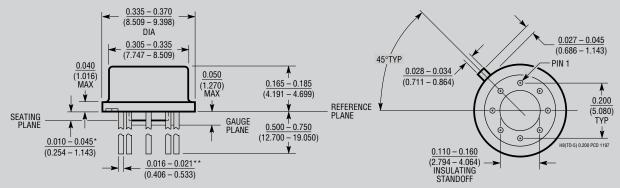


#### DC Accurate, 10Hz, 7th Order Lowpass Bessel Filter



### PACKAGE DESCRIPTION

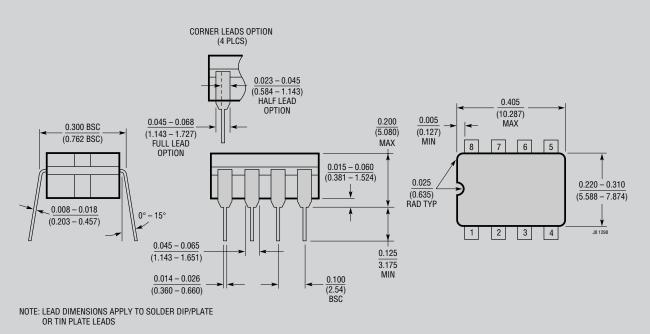
#### H Package 8-Lead TO-5 Metal Can (.200 Inch PCD) (Reference LTC DWG # 05-08-1320)



- \*LEAD DIAMETER IS UNCONTROLLED BETWEEN THE REFERENCE PLANE AND 0.045" BELOW THE REFERENCE PLANE
- \*\*FOR SOLDER DIP LEAD FINISH, LEAD DIAMETER IS  $\frac{0.016-0.024}{(0.406-0.610)}$

#### J8 Package 8-Lead CERDIP (Narrow .300 Inch, Hermetic)

(Reference LTC DWG # 05-08-1110)



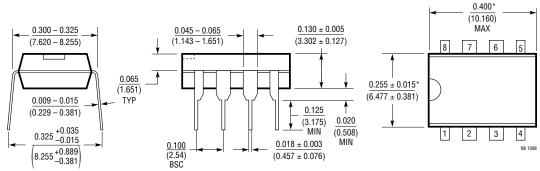
**OBSOLETE PACKAGES** 

LINEAR

### PACKAGE DESCRIPTION

#### N8 Package 8-Lead PDIP (Narrow .300 Inch)

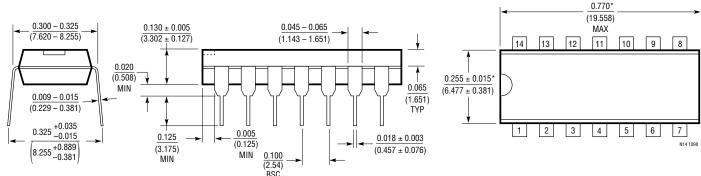
(Reference LTC DWG # 05-08-1510)



<sup>\*</sup>THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010 INCH (0.254mm)

#### N Package 14-Lead PDIP (Narrow .300 Inch)

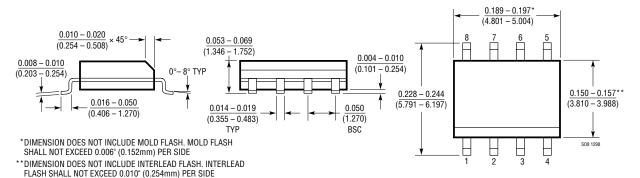
(Reference LTC DWG # 05-08-1510)



\*THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010 INCH (0.254mm)

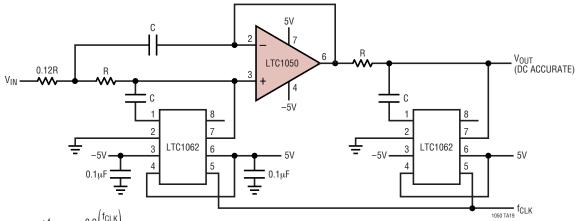
# \$8 Package 8-Lead Plastic Small Outline (Narrow .150 Inch)

(Reference LTC DWG # 05-08-1610)





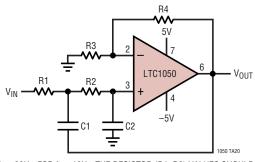
#### DC Accurate 10th Order Max Flat Lowpass Filter



- f<sub>CUTOFF</sub> = 0.9 • RC =  $\frac{0.2244}{f_{CUTOFF}}$
- 60dB/0CT. SLOPE
- PASSBAND ERROR <0.1dB FOR  $0 \le f \le 0.67 f_{CUTOFF}$
- THD = 0.04%, WIDEBAND NOISE =  $120\mu V_{RMS}$
- $\bullet$  f<sub>CLK</sub>  $\cong$  100kHz

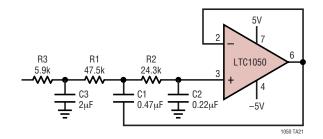
#### DC Accurate, Noninverting 2nd Order Lowpass Filter

#### Gain of 1, 10Hz 3rd Order Bessel DC Accurate Lowpass Filter



Q = 0.707,  $f_C$  = 20Hz. FOR  $f_C$  = 10Hz, THE RESISTOR (R1, R2) VALUES SHOULD BE DOUBLED

COMPONENT VALUES						
DC GAIN	R3	R4	R1	R2	C1	C2
1	∞	0	32.4k	18.7k	0.47μF	0.22μF
2	10k	10k	11.8k	24.3k	0.47μF	0.47μF
4	10.5k	31.6k	18.7k	34.8k	0.22μF	0.47μF
6	10.2k	51.1k	14k	46.4k	0.22μF	0.47μF
8	10.2k	71.5k	11.8k	54.9k	0.22μF	0.47μF
10	10.1k	90.9k	10.5k	61.9k	0.22μF	0.47μF



## **RELATED PARTS**

PART NUMBER	DESCRIPTION	COMMENTS
LTC1051	Dual Zero-Drift Op Amp's	Dual Version of the LTC1050
LTC2050	Zero-Drift Op Amp	SOT-23 Package
LTC2051	Zero-Drift Op Amp's	Dual Version of the LTC2050 in an MS8 Package
LTC2053	Zero-Drift Instrumentation Amp	110dB CMRR, MS8 Package, Gain Programmable